

DETAILED ACTION

Claims 1-15 are now rejoin to a group of product claims 16-29, and 31-36.

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Mr. Clement A. Berard (Reg. No. 29, 613) on July 19, 2003.

The application has been amended as follows:

Please, cancel claims 30, 37-51 without prejudice.

Claims 32-36, line 1, please change "of claim 30" to --of claims 31--

Claim 1, line 19, change "a substrate" to --the substrate--.

Claim 16, line 12, and claim 23, line ¹³14, change "an electronic or a substrate" to --
the electronic ^{device} or the substrate--.

Allowable Subject Matter

2. Claims 1-29, and 31-36 are allowed.

The following is an examiner's statement of reasons for allowance:

Corrected copy of p. 4 of CMPTC of 5/6/03.
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15. The electronic package of claim 14 wherein said second means for connecting includes connections of one of solder and electrically-conductive adhesive joining proximate corresponding ones of said conductive vias to the contacts of said substrate.
16. (Amended) A solderable flexible adhesive interposer comprising:
 - at least one layer of flexible dielectric adhesive having a modulus of elasticity less than about 35,000 kg/cm² (about 500,000 psi),
 - a plurality of conductive vias through said layer of flexible dielectric adhesive, said plurality of conductive vias being of a flexible electrically conductive adhesive having a modulus of elasticity less than about 35,000 kg/cm² (about 500,000 psi) and being in a pattern adapted for connection to contacts of an electronic device or a substrate, and
 - a solderable electrically conductive metal formed on at least one exposed surface of said conductive vias and in electrical contact therewith,
 - wherein at least one end of the plurality of conductive vias includes contacts adapted to be soldered to an electronic device or a substrate.
17. The solderable flexible adhesive interposer of claim 16 wherein said plurality of conductive vias are in a pattern corresponding to a pattern of contacts of one of an electronic device and a substrate, said solderable flexible adhesive interposer further comprising patterned metal conductors on one surface of said layer of flexible dielectric adhesive fanning out from at least ones of said conductive vias to locations corresponding to the pattern of contacts of the other one of an electronic device and a substrate.
18. The solderable flexible adhesive interposer of claim 16 wherein at least one of said flexible dielectric adhesive and said flexible conductive adhesive has a modulus of elasticity less than about 7,000 kg/cm² (about 100,000 psi).